



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



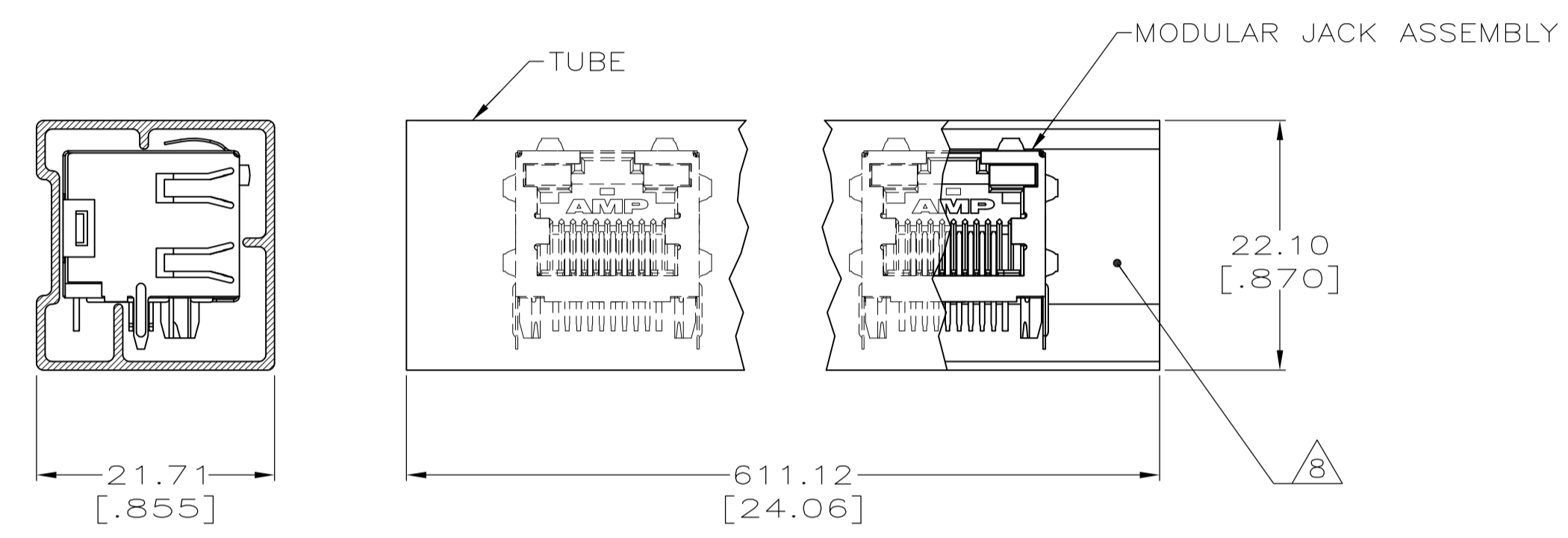
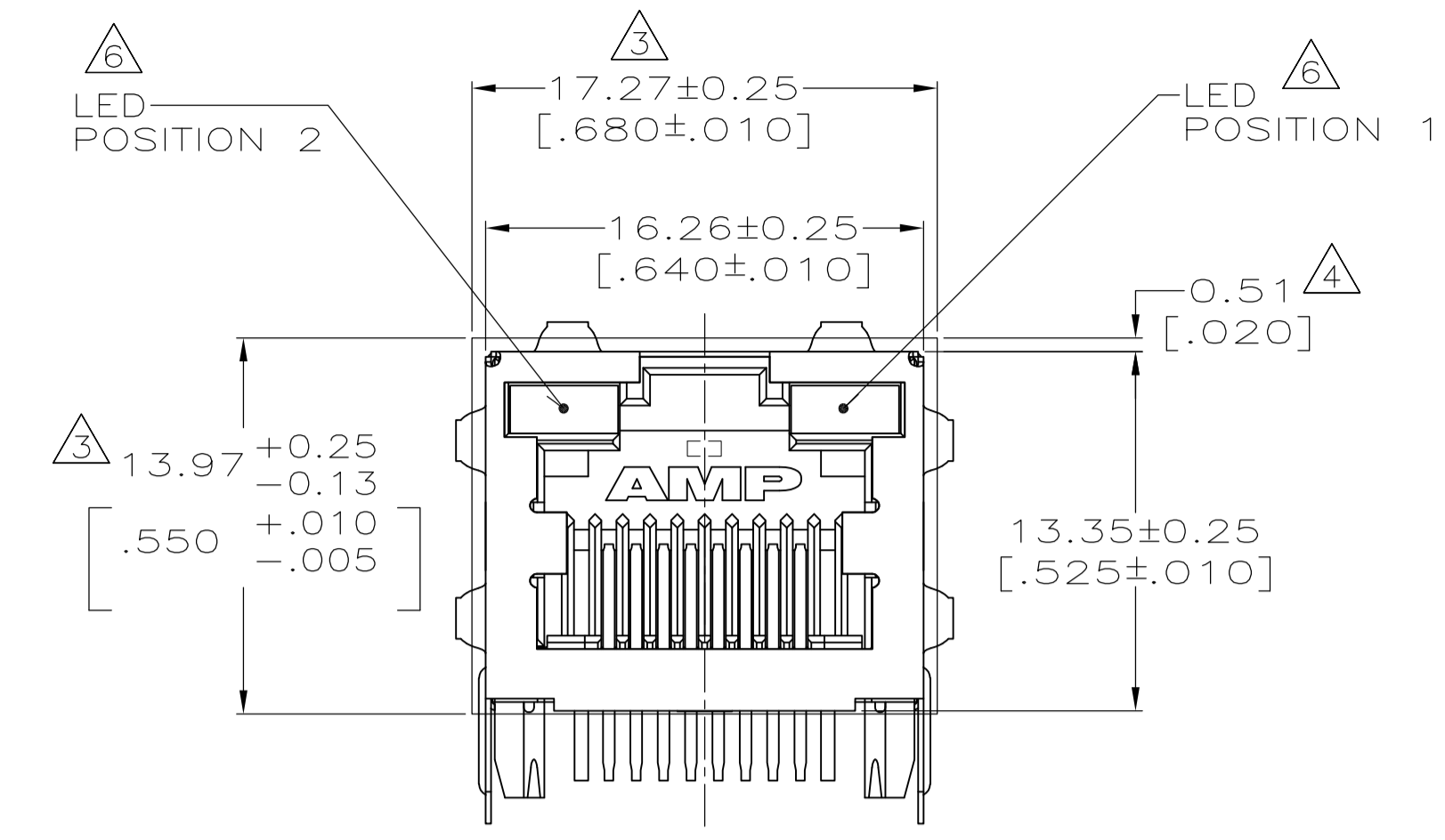
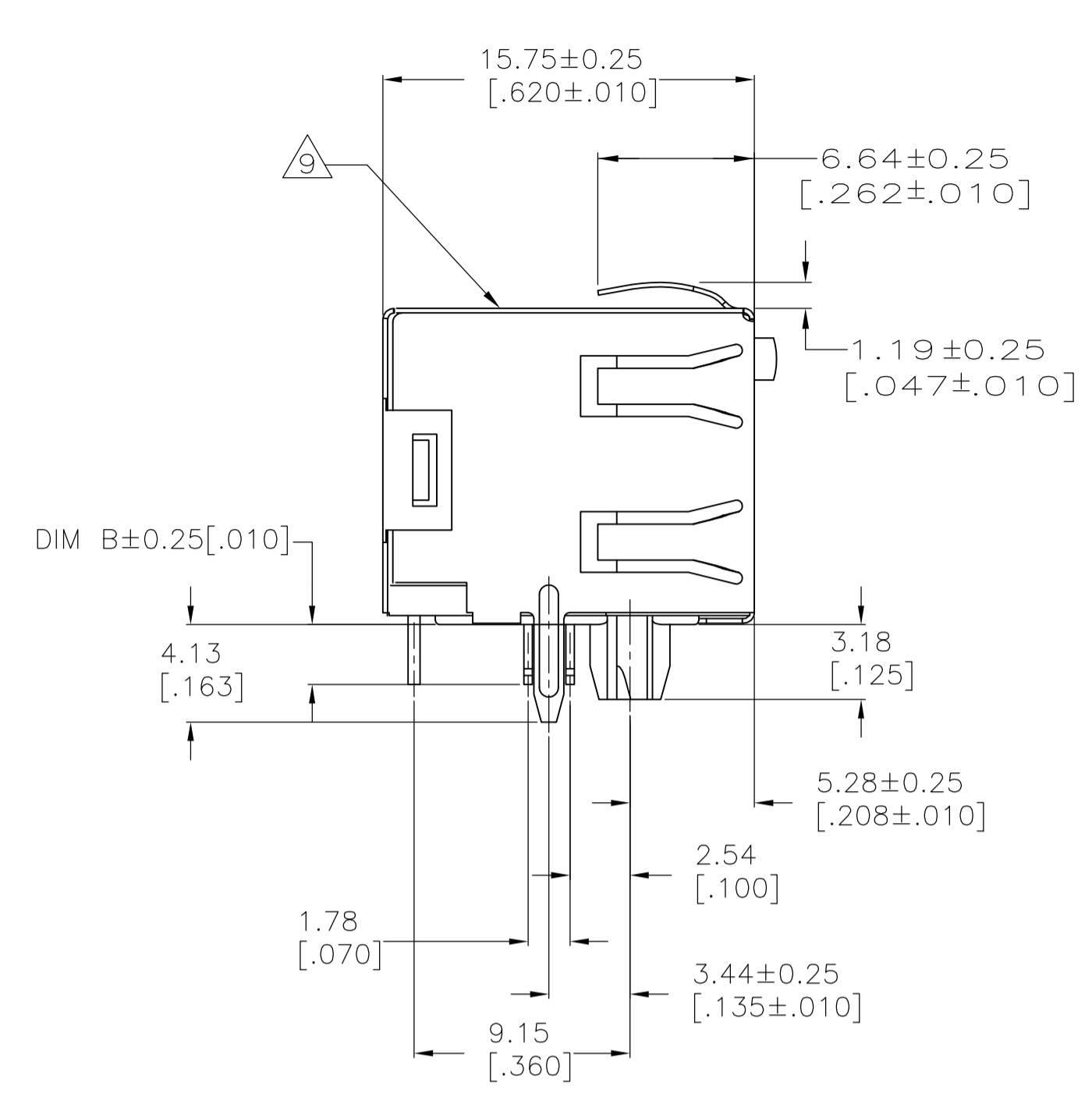
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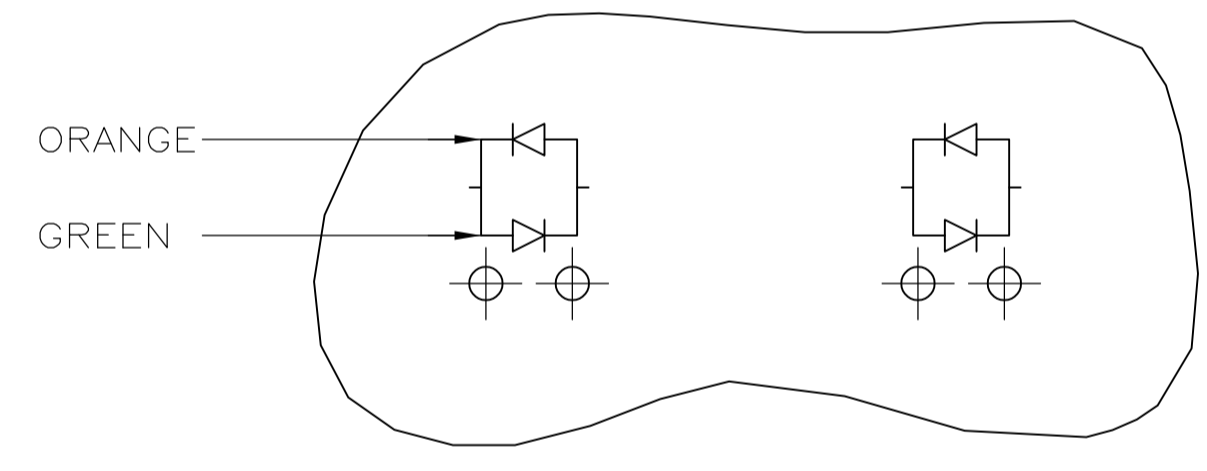
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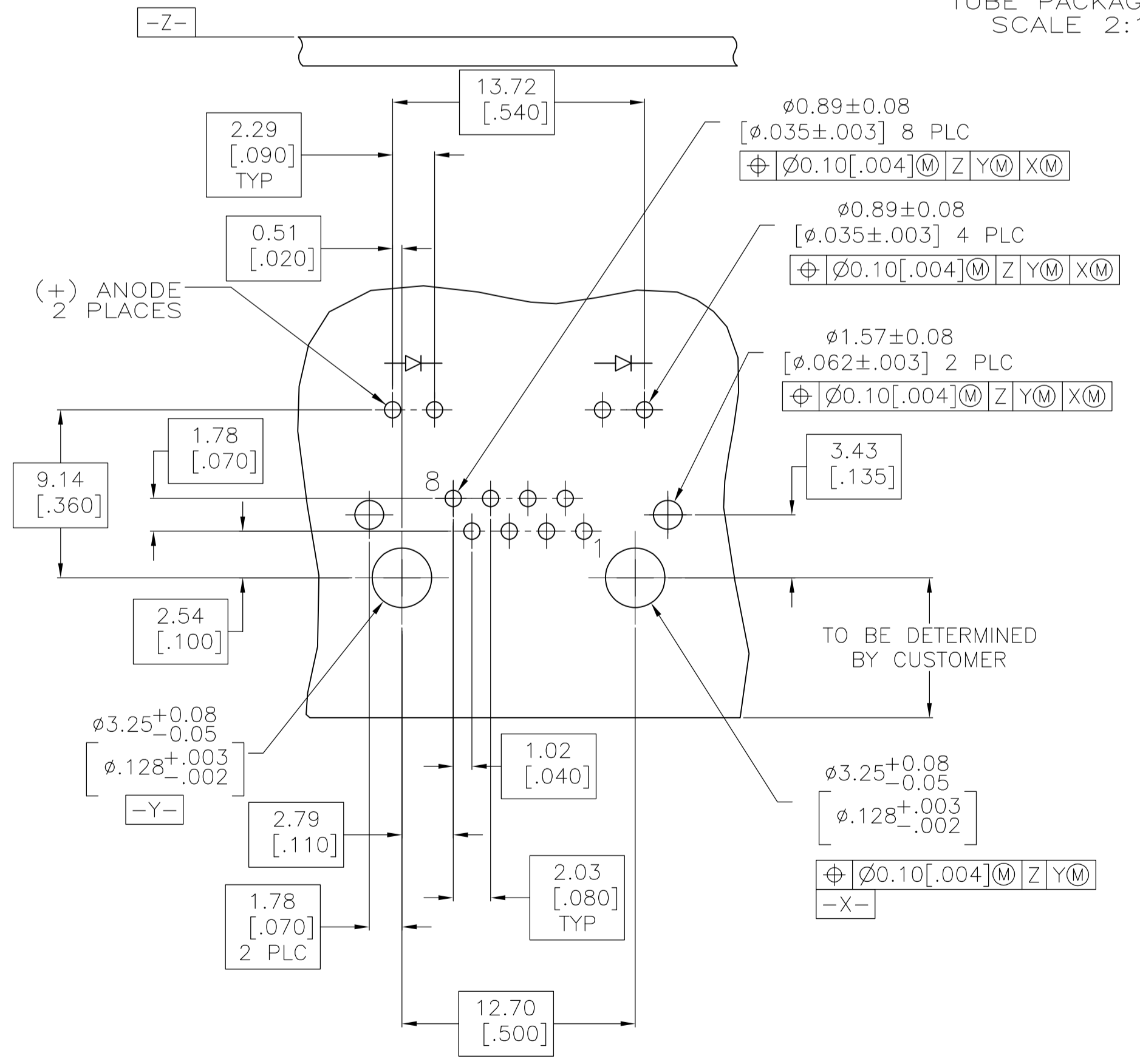




DETAIL A
TUBE PACKAGING
SCALE 2:1



LED CURRENT DIAGRAM
406507-7, 1-406507-7,
AND 3-406507-7



RECOMMENDED PRINTED CIRCUIT BOARD
(COMPONENT SIDE)

- △ MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK (SEE P/N TABLE) IN SOLDER AREA. 1.27µm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL.
SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PLATED WITH 8.89µm[.000350] TIN/COPPER OVER 2.03µm[.000080] SILVER OVER 1.02µm[.000040] NICKEL UNDERPLATE OVER 2.03µm[.000080] COPPER UNDERPLATE.
- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- 5. 0.051[.002] WHITE POLYESTER INSULATOR APPLIED TO BACK OF HOUSING.
- △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- 7. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- △ PACKAGED 30 PIECES PER TUBE. SEE DETAIL "A".
- △ MANUFACTURING DATE CODE:
LOCATED APPROX. AS SHOWN.
FIRST 2 DIGITS = LAST 2 DIGITS OF YEAR.
NEXT 2 DIGITS = MANUFACTURING WORK WEEK.
LAST DIGIT = DAY OF WEEK WITH SUNDAY = 1.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

TERMINAL LEAD PLATING	DIM B SOLDER TAIL LENGTH	PACKAGING	INDICATOR COLOR		PART NUMBER	
TIN-LEAD	2.54 [.100]	△ TUBE	GREEN	YELLOW	7-406507-4	
MATTE TIN	3.05 [.120]	TRAY	ORANGE/GREEN	ORANGE/GREEN	3-406507-7	
△ OBSOLETE	MATTE TIN	3.05 [.120]	TRAY	GREEN	GREEN	3-406507-5
△ OBSOLETE	MATTE TIN	3.05 [.120]	TRAY	GREEN	YELLOW	3-406507-4
△ OBSOLETE	MATTE TIN	3.05 [.120]	TRAY	YELLOW	GREEN	3-406507-1
MATTE TIN	2.54 [.100]	△ TUBE	GREEN	YELLOW	2-406507-4	
△ OBSOLETE	MATTE TIN	2.54 [.100]	TRAY	ORANGE/GREEN	ORANGE/GREEN	1-406507-7
MATTE TIN	2.54 [.100]	TRAY	YELLOW	YELLOW	1-406507-6	
MATTE TIN	2.54 [.100]	TRAY	GREEN	GREEN	1-406507-5	
△ OBSOLETE	MATTE TIN	2.54 [.100]	TRAY	GREEN	YELLOW	1-406507-4
△ OBSOLETE	MATTE TIN	2.54 [.100]	TRAY	YELLOW	-	1-406507-3
MATTE TIN	2.54 [.100]	TRAY	-	GREEN	1-406507-2	
MATTE TIN	2.54 [.100]	TRAY	YELLOW	GREEN	1-406507-1	
△ OBSOLETE	TIN-LEAD	2.54 [.100]	TRAY	ORANGE/GREEN	ORANGE/GREEN	406507-7
△ OBSOLETE	TIN-LEAD	2.54 [.100]	TRAY	YELLOW	YELLOW	406507-6
△ OBSOLETE	TIN-LEAD	2.54 [.100]	TRAY	GREEN	GREEN	406507-5
△ OBSOLETE	TIN-LEAD	2.54 [.100]	TRAY	GREEN	YELLOW	406507-4
△ OBSOLETE	TIN-LEAD	2.54 [.100]	TRAY	YELLOW	-	406507-3
△ OBSOLETE	TIN-LEAD	2.54 [.100]	TRAY	-	GREEN	406507-2
△ OBSOLETE	TIN-LEAD	2.54 [.100]	TRAY	YELLOW	GREEN	406507-1

THIS DRAWING IS A CONTROLLED DOCUMENT. DIN T SPRINKLE 15SEP97. CHK T SPRINKLE 15SEP97. APVD M DERSTINE 090C197. NAME: INVERTED MODULAR JACK ASSEMBLY, 1X1, SHIELDED, PANEL GROUND, LED, INSULATOR. PRODUCT SPEC: 108-1163-4. APPLICATION SPEC: 114-2154. SIZE: A1. WEIGHT: -. DRAWING NO: 00779. CUSTOMER DRAWING. SCALE: 4:1. SHEET: 1 OF 1. REV: K4.